

Color Type

U

Е

В

Datasheet

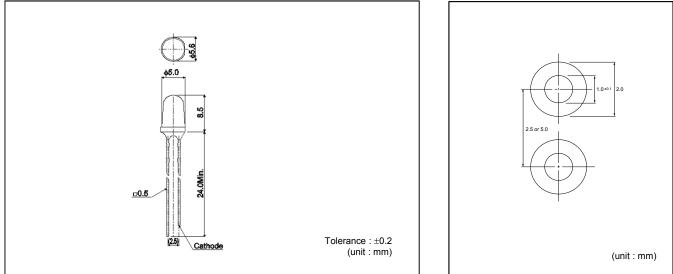
#### Features

Dimensions

Viewing angle 2θ 1/2 : 10°

# •Outline

## •Recommended Solder Pattern



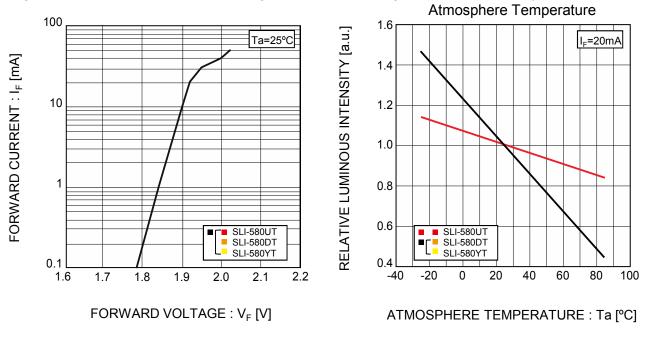
# Specifications

Viewing angle 20 1/2 / 10°: High brightness

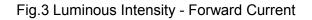
				Abs	solute Max	ximum Ra	atings (Ta=25°0	C)		Ele	ectrical	and O	otical Characte	eristics	(Ta=25	°C)		
Part No.	Chip	Emitting	Power	Forward	Peak Forward	Reverse	Operating Temp	Storage Temp.	Forward	Voltag V <sub>F</sub>	Reverse	Current I <sub>R</sub>	Dominant Wavel	ength λD	Lumino	ous Inte	nsity I <sub>V</sub>	
i dittito.	Structure	Color	Dissipation			Voltage		<b>o</b> .	Тур.	$I_{F}$	Max.	$V_R$	Тур.	١ <sub>F</sub>	Min.	Тур.	I <sub>F</sub>	
			$P_D(mW)$	I <sub>F</sub> (mA)	I <sub>FP</sub> (mA)	$V_{R}(V)$	Topr(°C)	Tstg(°C)	(V)	(mA)	(μA)	(V)	(nm)	(mA)	(mcd)	(mcd)	(mA)	
SLI-580UT		Red											620		2000			
SLI-580DT	AlGaInP on GaAs	Orange	125	50	200* <sup>2</sup>	9	$-30\ to\ +85$	-40 to +100	1.9		100	9	605		1350	5000		
SLI-580YT		Yellow											587		1550			
SLA-580MT	GaP	Yellowish Green	75	25	60* <sup>1</sup>	4	-25 to $+85$	-30 to +100	2.3	2.3 20	10	4	572	20	200	470	20	
SLA580ECT		Bluish							3.3	20			527	20	3000	8000		
SLA580EC4T	InGaN	Green	120	30	100* <sup>2</sup>	5	–20 to +80	30 to 100	3.2		100	5	521		2000	4500		
SLA580BCT	indan			120	30	100**	5	-20 10 +00	-30 to +100	3.3		100	5	470		900	2500	
SLA580BC4T		Dide	Blue						3.2				770		610	1500		

\*1:Duty1/5, 200Hz \*2:Duty1/10, 1kHz

# •Electrical Characteristics Curves



#### Fig.1 Forward Current - Forward Voltages



2.5

2.0

1.5

1.0

0.5

0

1

RELATIVE LUMINOUS INTENSITY [a.u.]



Ta=25⁰C

SLI-580UT

SLI-580DT

SLI-580YT

40

50

30

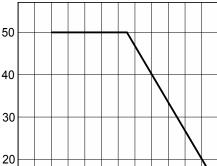
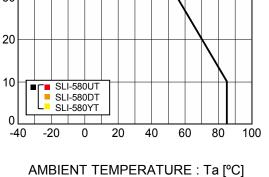


Fig.4 Derating

Fig.2 Luminous Intensity -





10

20

FORWARD CURRENT : I<sub>F</sub> [mA]

# Electrical Characteristics Curves

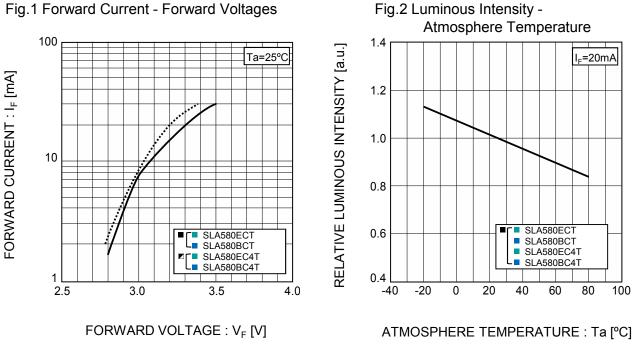
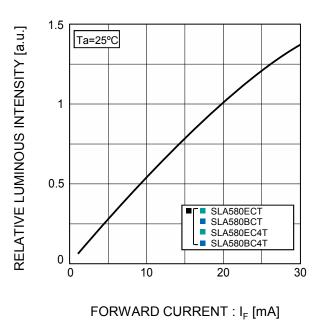
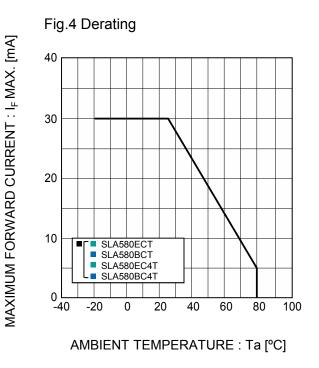


Fig.1 Forward Current - Forward Voltages

Fig.3 Luminous Intensity - Forward Current





# Electrical Characteristics Curves

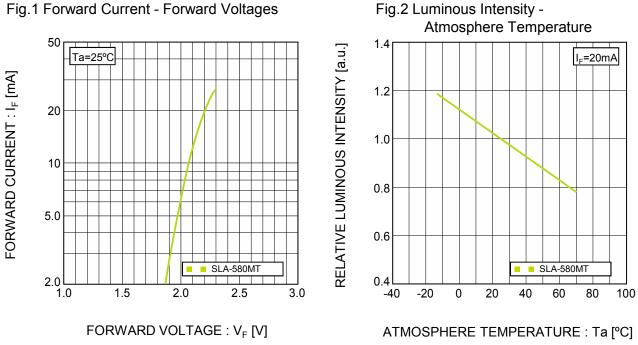


Fig.1 Forward Current - Forward Voltages

Fig.3 Luminous Intensity - Forward Current

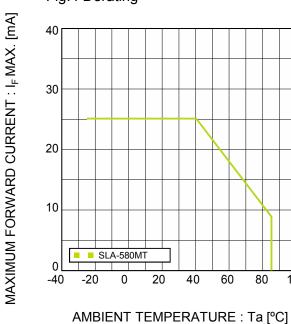
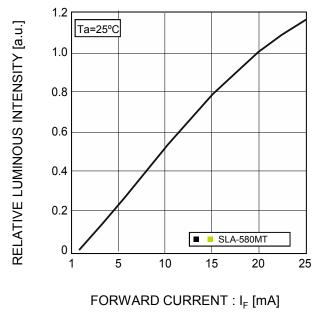


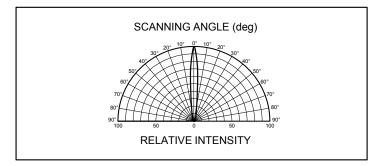
Fig.4 Derating



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100

## •Viewing Angle



# •Rank Reference of Brightness

Red (U)													(Ta=25⁰C,	I <sub>F</sub> =20mA)
Rank	XE	XF	XG	XH	XJ	ΧК	ХL	XM	XN	XP	XQ	XR	XS	XT
lv (mcd)	47 to 68	68 to 100			220 to 330	330 to 470	470 to 680	680 to 1000	1000 to 1500	1500 to 2200	2200 to 3300	3300 to 4700		6800 to 10000
SLI-580UT														

Orange (D	))												(Ta=25⁰C,	I <sub>F</sub> =20mA)
Rank	XE	XF	XG	XH	XJ	ΧК	XL	XM	XN	XP	XQ	XR	XS	XT
lv (mcd)	47 to 68	68 to 100	100 to 150		220 to 330	330 to 470	470 to 680	680 to 1000	1000 to 1500	1500 to 2200	2200 to 3300	3300 to 4700	4700 to 6800	6800 to 10000
SLI-580DT	00	100	150	220	330	470	000	1000	1500	2200	3300	4700	0800	10000

#### Yellow (Y)

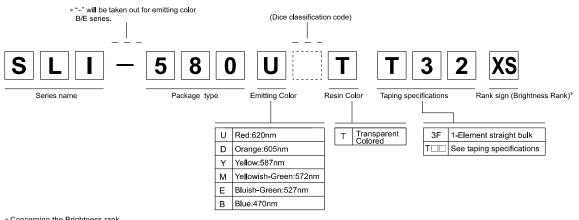
													(Ta=25°C,	$I_F = 20 \text{mA}$
Rank	XE	XF	XG	XH	XJ	ΧК	ХL	XM	XN	XP	XQ	XR	XS	XT
lv (mcd)	47 to 68	68 to 100	100 to 150	150 to 220	220 to 330			680 to 1000	1000 to 1500		2200 to 3300	3300 to 4700		6800 to 10000
SLI-580YT														

#### Green(M,E)

Green(M,E	E)																	(Ta=25°C	, I <sub>F</sub> =20mA)
Rank	XA	XB	XC	XD	XE	XF	XG	XH	XJ	ΧК	ХL	ХM	XN	XP	XQ	XR	XS	XT	XU
lv (mcd)	10 to 15	15 to 22	22 to 33			68 to 100					470 to 680	680 to 1000			2200 to 3300			6800 to 10000	10000 to 15000
SLA580ECT																			
SLA580EC4T																			
SLA-580MT																			

Blue (B)											(Ta=25°C	, I <sub>F</sub> =20mA)
Rank	XH	ΓX	ΧК	XL	XM	XN	XP	XQ	XR	XS	ХТ	XU
lv (mcd)	150 to 220	220 to 330	330 to 470		680 to 1000	1000 to 1500		2200 to 3300	3300 to 4700			10000 to 15000
SLA580BCT												
SLA580BC4T												

#### Part No. Construction



Concerning the Brightness rank
Please refer to the rank chart above for luminous intensity classification.

Part name is individual for each rank.
When shipped as sample, the part name will be a representative part name.
General products are free of ranks. Please contact sales if rank appointment is needed.

< No good >

To be fixed

### •Attention Points In Handling

Visual light emitting diode does not contain reinforcement materials such as glass fillers. Therefore if sudden thermal and mechanical shock are given, destruction or inferiority of luminous intensity may occur. Please take care of the handling.

#### **FIXATION METHOD**

#### **1. ATTENTION POINTS**

(1) Please do not give excessive heat over storage temperature to resin. In case that the product has to be heated in oven for the glue fixing of surface mount pats, this LED should be mounted after the glue fixing.

< Good >

To be fixed

(2) Please avoid stress to resin at high temperature.

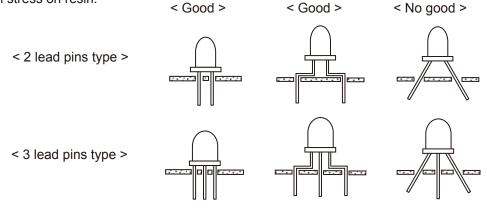
#### 2. TERMINATION PROCESSING

- (1) In case of termination processing, please fix the termination
- (2) Processing position, and process the reverse side of LED body.
   If stress is given during processing, It may cause
  - non-lighting failure.
- (3) Please process before soldering.

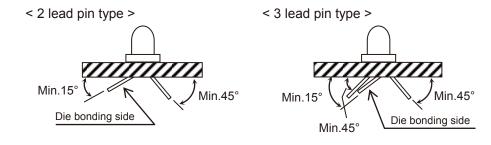
#### 3. ASSEMBLY ON PC BOARD

(1) In case of soldering on PCB, If the operation is done with stress, it may cause non-lighting failure during soldering or using.

Please design the through-holes of PCB suitable for lead pins space or lead pins space after formin to avoid the physical stress on resin.



 (2) Using spacer between LED's body and PCB is recommended. In case of direct mount on PCB(SLR/SLI-343 series), please take care about clinch of led pins to avoid the remained stress and solder heat stress. Enough evaluation is requested before deciding assembly and soldering conditions. Please consult with us if any problems in the evaluation stage.



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#### 4. SOLDERING (Sn-3Ag-0.5Cu)

- (1) Please make soldering rapidly under the following temperature and time conditions.
- (2) Please avoid stress to LED lamp during soldering.
- (3) In case of double peak flow soldering, the temperature gap during 1st and 2nd soldering to be less than 100 degree C.

ARTI	ICLE	SOLDERING TEMP	OPERATION TIME	Remarks
	Pre-heat	Max. 100°C	60sec Max.	-
Soldering Dip	Soldering Bath	Max. 265°C	5sec Max.	In case of double peak flow soldering, the operation time is counted from the beginning of 1st peak to the end of 2nd peak.
Solderi	ng Iron	Max. 400°C	3sec Max.	The iron should not touch the LED's body.

#### <Recommendable soldering conditions>

#### 5. CLEANING

In case of cleaning, some solvents may cause damage of resin or cause non-lighting failure, so please check the solvent before actual use.

The recommendable cleaning solvent is alcoholic one such as isopropyl alcohol.

#### <RECOMMENDABLE CLEANING CONDITIONS>

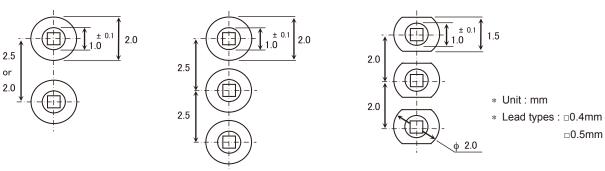
METHOD	CONDITIONS					
Cleaning by solvent	Temperature of solvent					
	Immersion time	: Max. 3min				
Cleaning by solvent	Ultrasonic out	: Ultrasonic out				
Cleaning by solvent	Cleaning time	: Max. 3min				

#### 6. RECOMMENDABLE ROUND PATTERN

Round pattern depends on the material PCB, density and circuit arrangement. Our recommendation is as follow :

< 2lead pin type >

< 3lead pin type/2.5mm pitch > < 3 lead pin type/2.0mm pitch >



#### **ATTENTION ON STORAGING**

Storage in dry box is most desirable, but if it is not possible, we recommend following conditions.

#### <RECOMMENDABLE STORAGE CONDITIONS>

ARTICLE	Temperature	Humidity	Expiration Date
CONDITIONS	5 to 30°C	Max.60%RH	Within 1 year

Poor storage conditions may cause some failure as bellow.

- (1) Lead pins may corrode if it is stored in the environment of high temperature and humidity and lead to defective soldering.
- (2) In case of soldering after LED's body absorb moisture highly, destruction or inferiority of luminous intensity may occur.



#### ■APPLICATION METHOD

#### 1. Precaution for Drive System and Off Mode

- Design the circuit without the electric load exceeding the ABSOLUTE MAXIMUM RATING that applies on the products.
- If drive by constant voltage, it may cause current deviation of the LED and result in deviation of luminous intensity, so we recommend to drive by constant current. (Deviation of VF Value will cause deviation of current in LED.)
- Furthermore, for off mode, please do not apply voltage neither forward nor reverse. Especially, for the products with the Ag-paste used in the die bonding, there's high possibility to cause electro migration and result in function failure.

#### 2. Operation Life Span

There's possibility for intensity of light drop according to working conditions and environments (applied current, surrounding temperature and humidity, corrosive gases ), please call our Sales staffs for inquiries about the concerned application below.

(1) Longtime intensity of light life

(2) On mode all the time

#### 3. Usage

The Product is LED. We are not responsible for the usage as the diode such as Protection Chip, Rectifier, Switching and so on.

#### OTHERS

#### 1. Surrounding Gas

Notice that if it is stored under the condition of acid gas (chlorine gas, sulfured gas) or alkali gas (ammonia), it may result in low soldering ability (caused by the change in quality of the plating surface ) or optical characteristics changes (light intensity, chrominance) and change in quality of die bonding (Ag-paste) aterials.

All of the above will cause function failure of the products.

Therefore, please pay attention to the storage environment for mounted product (concern the generated gas of the surrounding parts of the products and the atmospheric environment).

#### 2. Electrostatic Damage

The product is part of semiconductor and electrostatic sensitive, there's high possibility to be damaged by the electrostatic discharge.

Please take appropriate measures to avoid the static electricity from human body and earthing setting of production equipment. The resistance values of electrostatic discharge (actual values) are different varies with products, therefore, please call our Sales staffs for inquiries.

#### 3. Electromagnetic Wave

Please concern the influence on LED in case of application with strong electromagnetic wave such as IH (Induction heating).

	Notes
1)	The information contained herein is subject to change without notice.
2)	Before you use our Products, please contact our sales representative and verify the latest specifications :
3)	Although ROHM is continuously working to improve product reliability and quality, semicon ductors can break down and malfunction due to various factors. Therefore, in order to prevent personal injury or fire arising from failure, please take safet measures such as complying with the derating characteristics, implementing redundant and fire prevention designs, and utilizing backups and fail-safe procedures. ROHM shall have no responsibility for any damages arising out of the use of our Poducts beyond the rating specified be ROHM.
4)	Examples of application circuits, circuit constants and any other information contained herein ar provided only to illustrate the standard usage and operations of the Products. The periphera conditions must be taken into account when designing circuits for mass production.
5)	The technical information specified herein is intended only to show the typical functions of an examples of application circuits for the Products. ROHM does not grant you, explicitly or implicitly any license to use or exercise intellectual property or other rights held by ROHM or any other parties. ROHM shall have no responsibility whatsoever for any dispute arising out of the use or such technical information.
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